

Ultrafast Avalanche SMD Rectifier



DO-214AC (SMA)

FEATURES

- Low profile package
- Ideal for automated placement
- Glass passivated pallet chip junction
- Low reverse current
- Soft recovery characteristics
- Ultrafast reverse recovery time
- Meets MSL level 1, per J-STD-020, LF maximum peak of 260 °C
- AEC-Q101 qualified
- Material categorization: for definitions of compliance please see www.vishay.com/doc?99912


RoHS
COMPLIANT

TYPICAL APPLICATIONS

For use in high frequency rectification of power supply, inverters, converters, and freewheeling diodes for consumer, automotive and telecommunication.

MECHANICAL DATA

Case: DO-214AC (SMA)

Molding compound meets UL 94 V-0 flammability rating

Base P/N-E3 - RoHS-compliant, commercial grade

Base P/NHE3 - RoHS-compliant, AEC-Q101 qualified

Terminals: Matte tin plated leads, solderable per J-STD-002 and JESD 22-B102

E3 suffix meets JESD 201 class 2 whisker test, HE3 suffix meets JESD 201 class 2 whisker test

Polarity: Color band denotes the cathode end

PRIMARY CHARACTERISTICS	
$I_{F(AV)}$	1.5 A
V_{RRM}	200 V, 400 V, 600 V
I_{FSM}	30 A
I_R	1.0 μ A
V_F at I_F	1.4 V
t_{rr}	75 ns
E_R	20 mJ
T_J max.	150 °C
Package	DO-214AC (SMA)
Diode variations	Single die

MAXIMUM RATINGS ($T_A = 25$ °C unless otherwise noted)					
PARAMETER	SYMBOL	BYG20D	BYG20G	BYG20J	UNIT
Device marking code		BYG20D	BYG20G	BYG20J	
Maximum repetitive peak reverse voltage	V_{RRM}	200	400	600	V
Average forward current	$I_{F(AV)}$	1.5			A
Peak forward surge current 10 ms single half sine-wave superimposed on rated load	I_{FSM}	30			A
Pulse energy in avalanche mode, non repetitive (inductive load switch off) $I_{(BR)R} = 1$ A, $T_J = 25$ °C	E_R	20			mJ
Operating junction and storage temperature range	T_J, T_{STG}	-55 to +150			°C



ELECTRICAL CHARACTERISTICS ($T_A = 25\text{ }^\circ\text{C}$ unless otherwise noted)							
PARAMETER	TEST CONDITIONS		SYMBOL	BYG20D	BYG20G	BYG20J	UNIT
Maximum instantaneous forward voltage	$I_F = 1\text{ A}$	$T_J = 25\text{ }^\circ\text{C}$	$V_F^{(1)}$	1.3			V
	$I_F = 1.5\text{ A}$			1.4			
Maximum DC reverse current	$V_R = V_{RRM}$	$T_J = 25\text{ }^\circ\text{C}$	I_R	1			μA
		$T_J = 100\text{ }^\circ\text{C}$		10			
Maximum reverse recovery time	$I_F = 0.5\text{ A}, I_R = 1.0\text{ A}, I_{rr} = 0.25\text{ A}$		t_{rr}	75			ns

Note(1) Pulse test: 300 μs pulse width, 1 % duty cycle

THERMAL CHARACTERISTICS ($T_A = 25\text{ }^\circ\text{C}$ unless otherwise noted)					
PARAMETER	SYMBOL	BYG20D	BYG20G	BYG20J	UNIT
Typical thermal resistance, junction to lead, $T_L = \text{const.}$	$R_{\theta JL}$	25			$^\circ\text{C/W}$
Typical thermal resistance, junction to ambient	$R_{\theta JA}^{(1)}$	150			$^\circ\text{C/W}$
	$R_{\theta JA}^{(2)}$	125			
	$R_{\theta JA}^{(3)}$	100			

Notes

- (1) Mounted on epoxy-glass hard tissue
(2) Mounted on epoxy-glass hard tissue, 50 mm² 35 μm Cu
(3) Mounted on Al-oxide-ceramic (Al₂O₃), 50 mm² 35 μm Cu

ORDERING INFORMATION (Example)				
PREFERRED P/N	UNIT WEIGHT (g)	PREFERRED PACKAGE CODE	BASE QUANTITY	DELIVERY MODE
BYG20D-E3/TR	0.064	TR	1800	7" diameter plastic tape and reel
BYG20D-E3/TR3	0.064	TR3	7500	13" diameter plastic tape and reel
BYG20DHE3/TR ⁽¹⁾	0.064	TR	1800	7" diameter plastic tape and reel
BYG20DHE3/TR3 ⁽¹⁾	0.064	TR3	7500	13" diameter plastic tape and reel

Note

(1) AEC-Q101 qualified



RATINGS AND CHARACTERISTICS CURVES ($T_A = 25\text{ }^\circ\text{C}$ unless otherwise noted)

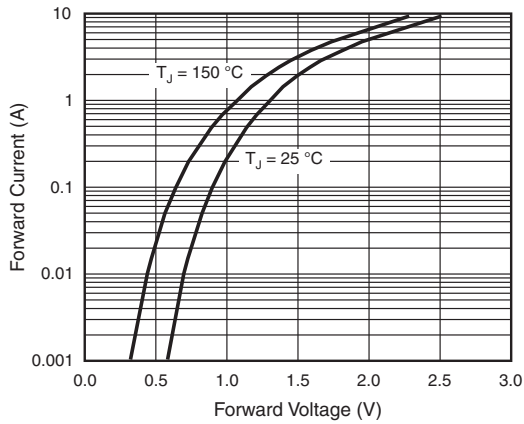


Fig. 1 - Forward Current vs. Forward Voltage

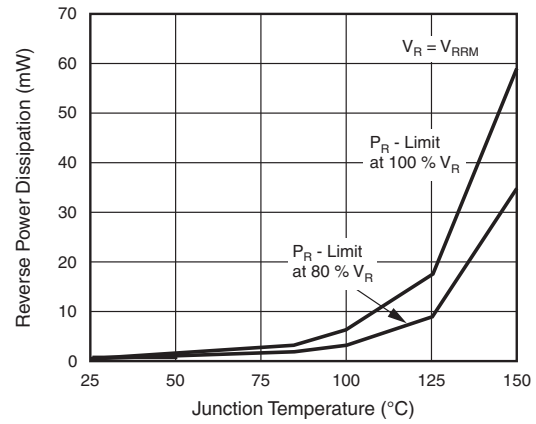


Fig. 4 - Max. Reverse Power Dissipation vs. Junction Temperature

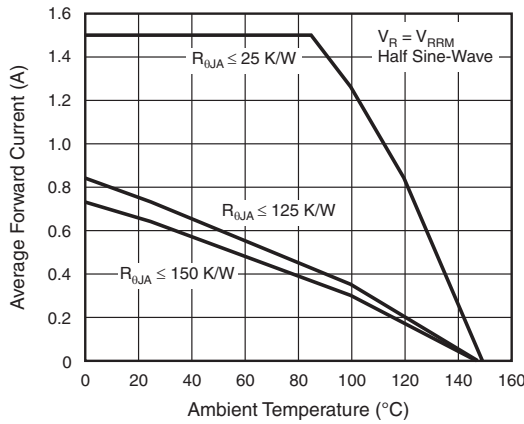


Fig. 2 - Max. Average Forward Current vs. Ambient Temperature

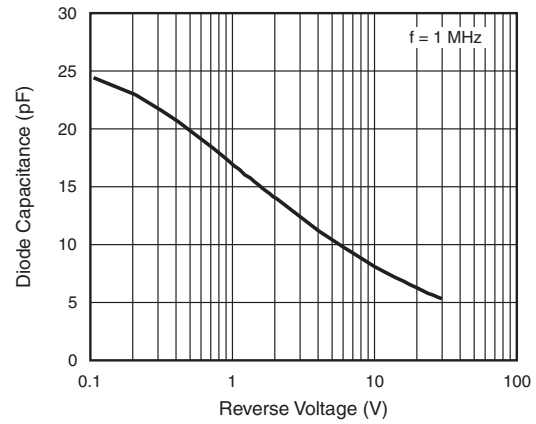


Fig. 5 - Diode Capacitance vs. Reverse Voltage

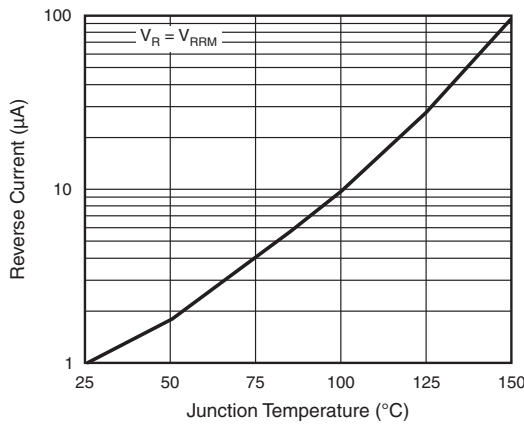


Fig. 3 - Reverse Current vs. Junction Temperature

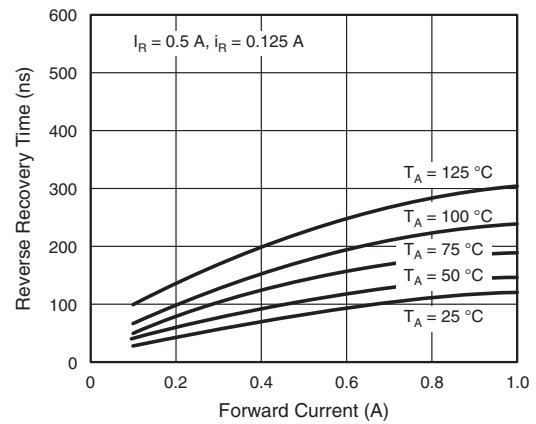


Fig. 6 - Reverse Recovery Time vs. Forward Current

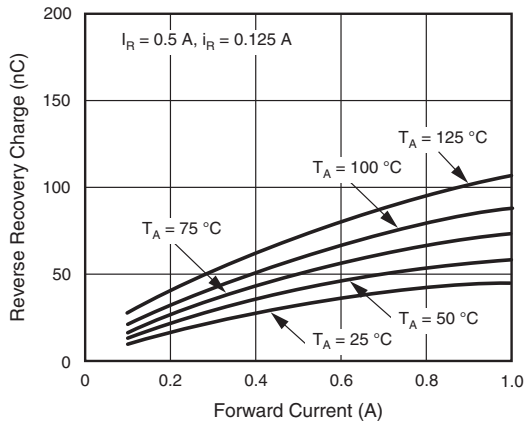


Fig. 7 - Reverse Recovery Charge vs. Forward Current

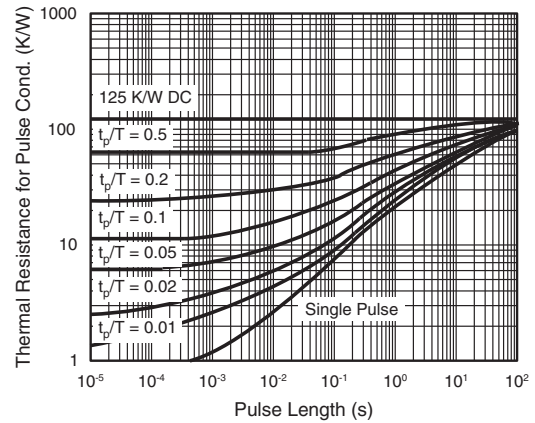
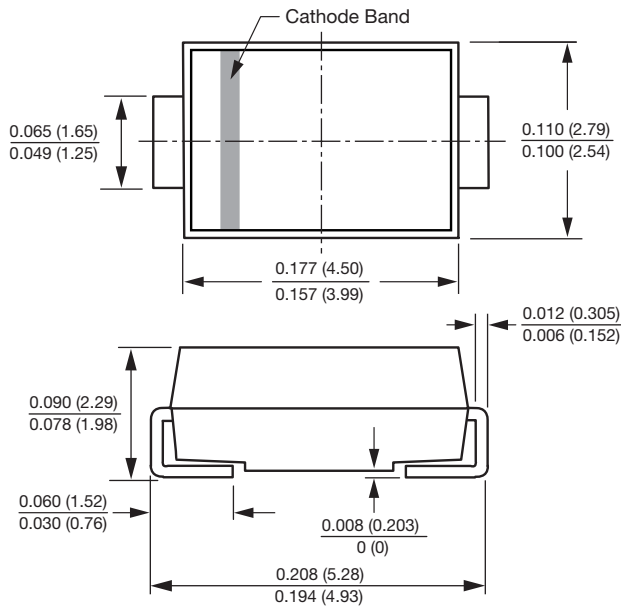


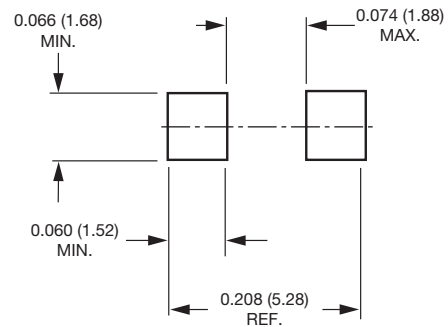
Fig. 8 - Thermal Response

PACKAGE OUTLINE DIMENSIONS in inches (millimeters)

DO-214AC (SMA)



Mounting Pad Layout





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